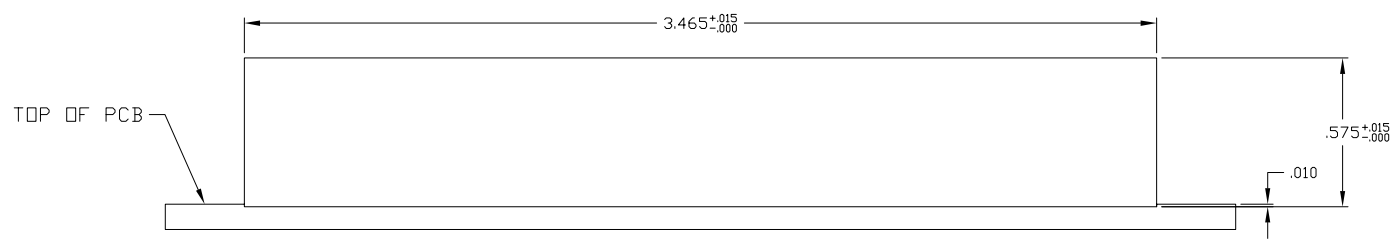
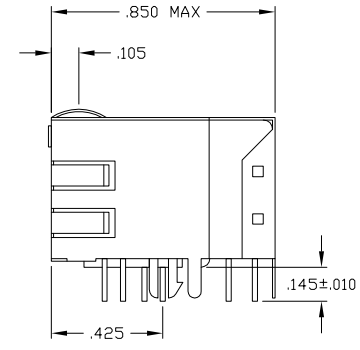
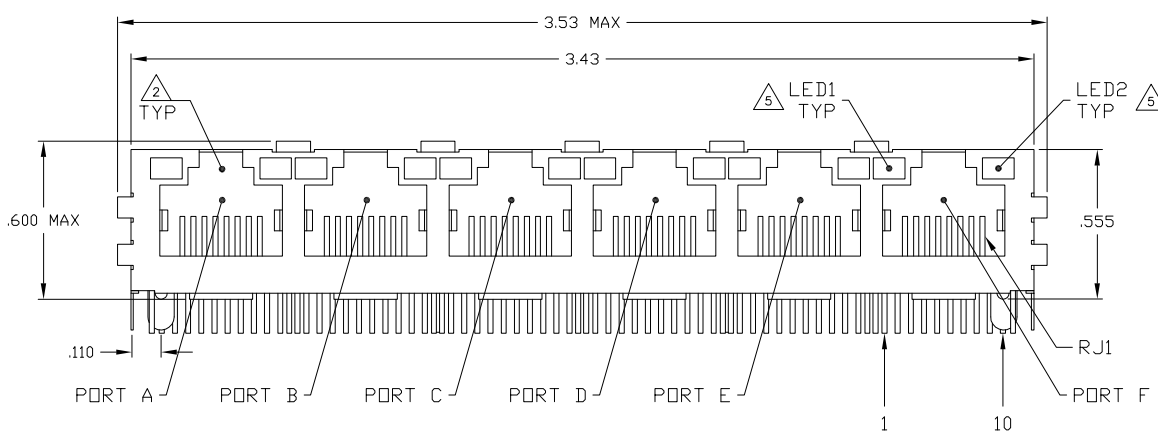
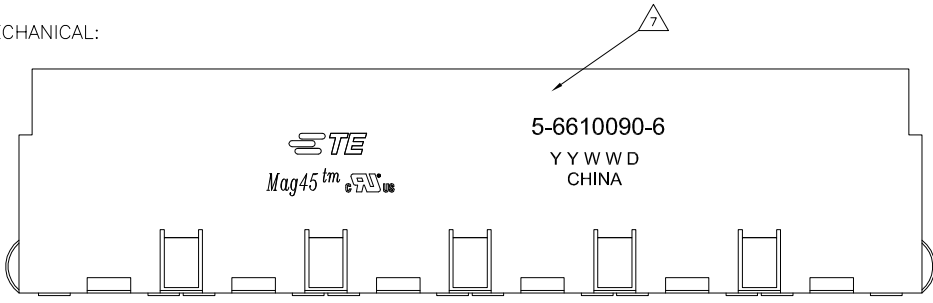


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LOC		REVISONS	
NO	DATE	DESCRIPTION	BY
AA	22		
B	ECO-09-005596		31MAY2009 VL LRF
C	ECO-11-013352		20MAY2011 EL LRF

MECHANICAL:



1X6 SUGGESTED PANEL CUTOUT

- MATERIALS:**
 -HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0
 -SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT
 NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 -MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL
 NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.
 SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 -LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL
 WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μIN MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP: CABLE): 1:1 ALL FOUR PAIRS
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
 -ALL FOUR PAIRS BI-DIRECTIONAL
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 12-20LOG(f/80)dB MIN FROM 4.0.1MHz TO 100MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50)dB MIN FROM 4.0.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- LEDS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA**
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ VF=5V
 FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ VF=5V
 FORWARD CURRENT (IF): YELLOW 13mA TYP @ VF=5V
- INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.**
- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.**
8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

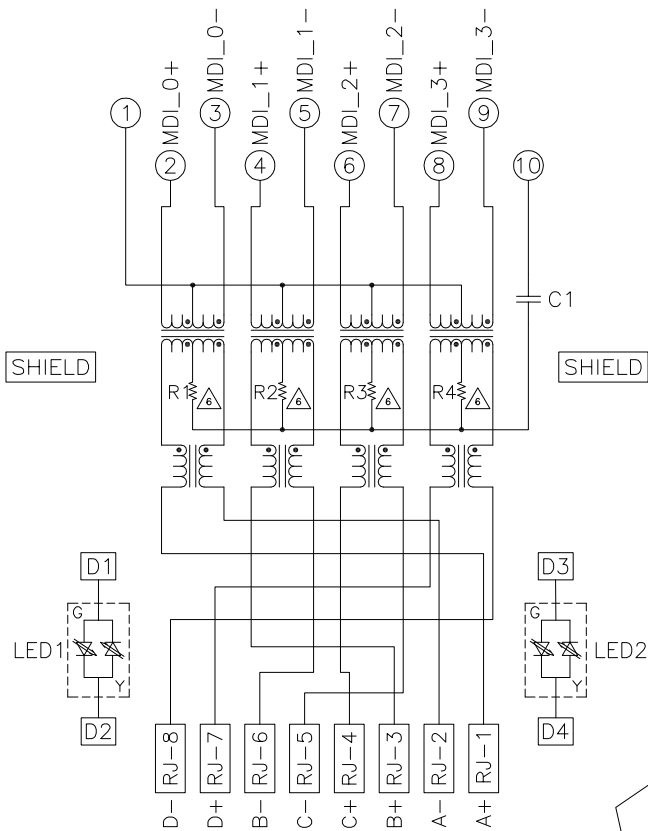
LED1	LED2	PART NUMBER
GREEN/YELLOW	GREEN/YELLOW	5-6610090-6

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNED BY: A. FERNANDEZ-RODRIGUEZ	DATE: 10MAR2009	NAME: 1X6 MAG45(TM) MODULAR JACK, 701 GIG SCHEMATIC, 701P1 SERIES MAG CIRCUIT (10 PIN HORIZONTAL), DECOUPLING CAP, SHIELDED, WITH G/Y - G/Y LEADS.
DRAWN BY: D. FAROLE	DATE: 10MAR2009	PRODUCT SPEC: 108-2100
CHECKED BY: D. FAROLE	DATE: 10MAR2009	APPLICATION SPEC: -
APPROVED BY: -	DATE: -	SIZE: A1
MATERIAL: -	FINISH: -	WEIGHT: -
CUSTOMER DRAWING		SCALE: 4:1

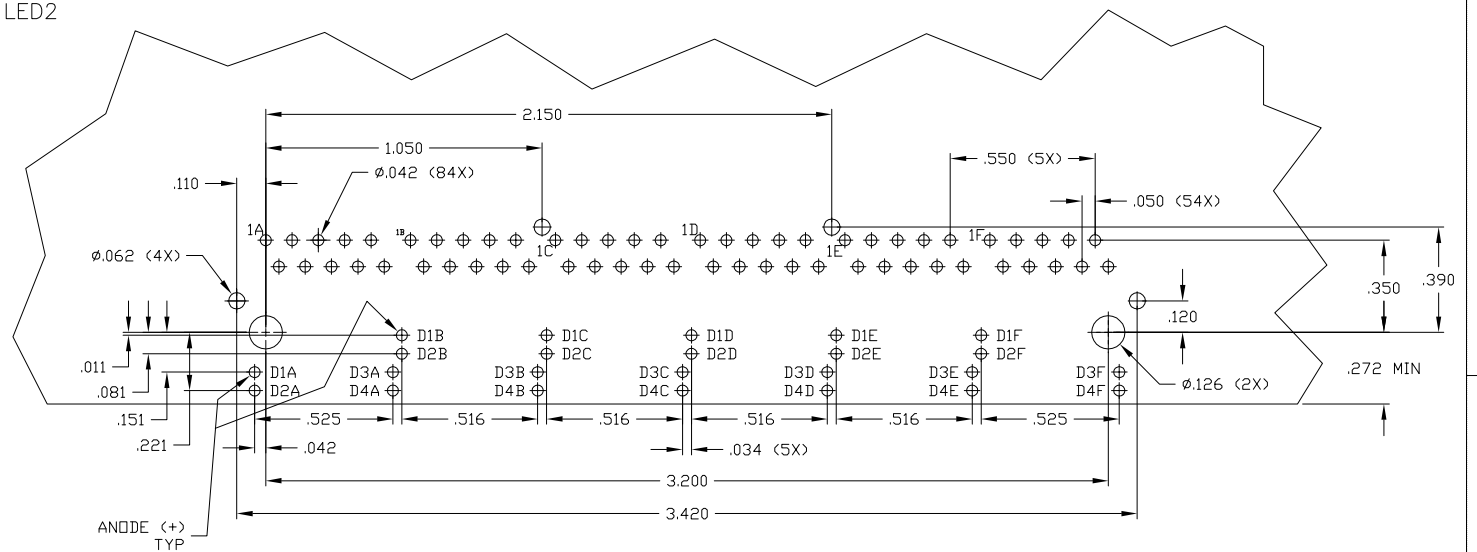
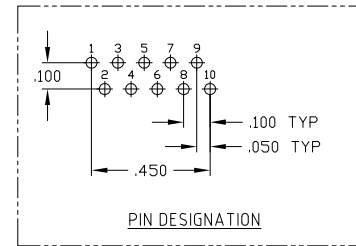
REV 1 OF 2

7G01P1 SERIES MAGNETIC CIRCUIT



C1 = 1000pF, 2kV DECOUPLING CAPACITOR

R1-R4 = 75 OHMS, 1/16 W RESISTORS



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	A	DATE	10MAR2008	TE Connectivity
DRAWN BY		A. FERNANDEZ	CHKD	D. FAROLE	10MAR2008	
DIMENSIONS:		D. FAROLE		DATE	10MAR2008	NAME 1X6 MAG45(TM) MODULAR JACK, 701 GIG SCHEMATIC, 701P1 SERIES MAG CIRCUIT (10 PIN HORIZONTAL), DECOUPLING CAP, SHIELDED, WITH G/Y - G/Y LEADS. APPLICATION SPEC 108-2100 SIZE DATE CODE DRAWING NO RESTRICTED TO A1 00779 C=6610090 CUSTOMER DRAWING SCALE 4:1 SHEET 2 of 2 REV C
INCHES		D. FAROLE		DATE	10MAR2008	
0.100 ± .005		D. FAROLE		DATE	10MAR2008	
0.100 ± .010		D. FAROLE		DATE	10MAR2008	